

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| L1 | 7664 | 257/779.ccls. or 257/781-784.ccls. or 257/787-790.ccls. or 257/723.ccls. or 257/734.ccls. or 257/678.ccls. | USPAT | OR | ON | 2007/02/16 21:40 |
| L2 | 68 | 1 and (foil adj (sheet layer film)) and (chip die component IC (integrated adj circuit)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/02/16 21:50 |
| L3 | 57 | 2 and solder\$4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/02/16 21:50 |
| L4 | 31 | 3 and (bond\$3 near pad\$2) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/02/16 21:40 |
| L5 | 30 | @ad <= "20040324" and 4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/02/16 21:23 |
| L6 | 37 | 3 and (bond\$3 near wir\$4) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/02/16 21:23 |
| L7 | 36 | @ad <= "20040324" and 6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/02/16 21:43 |
| L8 | 0 | (10/807,527).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/02/16 21:29 |

EAST Search History

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|-----|------|---|---|----|-----|------------------|
| L9 | 1 | 10/807,527 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/02/16 21:29 |
| L10 | 3525 | 257/779.ccls. or 257/781-784.ccls. or 257/787-790.ccls. or 257/723. ccls. or 257/734.ccls. or 257/678. ccls. | US-PGPUB | OR | ON | 2007/02/16 21:40 |
| L11 | 38 | 10 and (foil adj (sheet layer film)) and (chip die component IC (integrated adj circuit)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/02/16 21:40 |
| L12 | 14 | 11 and (bond\$3 near pad\$2) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/02/16 21:42 |
| L13 | 7 | @ad <= "20040324" and 12 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/02/16 21:41 |
| L14 | 3717 | 438/110-114.ccls. or 438/118-119. ccls. or 438/127.ccls. | USPAT | OR | ON | 2007/02/16 21:50 |
| L15 | 41 | 14 and (foil adj (sheet layer film)) and (chip die component IC (integrated adj circuit)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/02/16 21:42 |
| L16 | 18 | 15 and (bond\$3 near pad\$2) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/02/16 21:42 |
| L17 | 18 | @ad <= "20040324" and 16 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/02/16 21:50 |
| L18 | 1435 | 438/110-114.ccls. or 438/118-119. ccls. or 438/127.ccls. | US-PGPUB | OR | ON | 2007/02/16 21:50 |

EAST Search History

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| L19 | 14 | 18 and (foil adj (sheet layer film)) and (chip die component IC (integrated adj circuit)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/02/16 21:50 |
| L20 | 12 | 19 and solder\$4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/02/16 21:50 |
| L21 | 7 | @ad <= "20040324" and 20 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/02/16 22:01 |
| S4 | 292 | (foil adj (sheet layer film)) with solder\$4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/02/16 02:56 |
| S5 | 844 | (foil adj (sheet layer film)) with (chip die component IC (integrated adj circuit)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/02/16 21:20 |
| S6 | 58 | S4 and S5 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/02/16 02:57 |
| S7 | 16 | S6 and (bond\$3 near pad\$2) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/02/16 21:21 |
| S8 | 14 | @ad <= "20040324" and S7 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/02/16 21:22 |